Thermal Management

- Thermally Conductive RTV Silicone
- Projection Tube Coolant
- Thermally Conductive Epoxy
- Silver Conductive Epoxy
- Carbon Conductive Grease
- Silicone Heat Transfer

ALL MG PRODUCTS

- Accessories
- Adhesives
- Brushes
- Cleaners / Degreasers
- Contact Cleaners
- Desoldering Braid
- Dusters & Circuit Coolers
- EMI / RFI Shielding
- Epoxies
- Flux and Flux Remover
- Glass & Screen Cleaners
- Lubricants
- Potting & Encapsulating
- Protective Coatings
- Pens
- Prototyping Materials
- RTV Silicones
- Specialized Cleaners
- Swabs
- Thermal Management
- Thermally Conductive Adhesives
- Wipes

Non-Silicone Heat Transfer Compound

8610 BUY NOW

- Special synthetic base, fortified with metal oxides and compounded to a paste-like consistency for ease of application
- High efficient thermal conductive properties
  - Means more rapid transfer of heat for longer component life
- High temperature stability
  - Provides physical properties of low bleed and low evaporation for long-term service in any application that requires Heat Sink Compound.
- Uses synthetic fluids and metal oxide fillers
  - Provides excellent conductive properties that exceed those of other heat sink formulas
- Will not dry, harden, melt or migrate in any heat sink application
- Compatible with metal and plastic components
- Meets MIL-DTL-47113D
- Also available in a silicone version

Benefits of Non Silicone Heat Transfer Compound OVER Silicone

No migration and component contamination.

Applications

- Typically, Heat Transfer Compounds (heat sink compounds) are used in OEM Electronic Component Plants to insure fast, accurate heat transfer in electronic components and circuitry
- Other used:
  - Semiconductor Mounting Devices
  - Thermal joints
  - Ballast heat transfer mediums
  - Power resistor mountings
  - Thermocouple wells
  - Transistor diodes & silicone rectifier base and mounting studs
  - ALL electric and electronic devices where efficient heat transfer cooling through thermal coupling is required

Quick Links

MSDS (PDF)
Material Safety Data Sheet

Info on dispensing equipment (Cammda)

View an animated demonstration of how to apply Silicone Heat Transfer Compound

Specifications

Physical Properties	Test Method	Non Silicone 8610	Silicone 860
Appearance	Visual	Off white / smooth paste	White paste
Consistency	ASTM D 217	310-320	
Specific Gravity @ 25°C (77°F)		2.5 min	2.3 min
Bleed % 24 hours @ 200°C	FTM-321	1.0% max	2.0% max
Bleed % 24 hours @ 200°C	FTM-321	1.0% max	2.0% max
Evaporation 24 hours @ 200°C	ASTM D-566	> 500°F (260°C)	
Max. operating temp.		200°C	200°C (consistent) 300°C intermittent
Electrical Properties	**Test Method**	**Non Silicone 8610**	**Silicone 860**
Thermal Conductivity	Hot Wire Method Heat Flow #36 °C	18.48 x 10^{-4} (K Factor, Cal/Sec cm•K	0.657 W/m•K
Dielectric Strength (0.05l gap)	ASTM D-149	350 V/MIL	400 V/MIL
Dielectric Constant @ 1000 Hz	ASTM D- 150	4.4	3.81
Dissipation Factor @ 1000 Hz	ASTM D 150	0.0021	0.0032
Resistivity @ 21°C	ASTM D 150	6.38 x 10^{13} Ohm/cm	1.5 x 10^{15} Ohm/cm

Available Sizes

Catalog Number	Sizes Available	Description
8610-60G	60g (2 oz)	Liquid - TUBE
8610-1P	1 pint (2.5 lbs)	Tub

